



GP
ELECTRONICS

GPT090N15NTH
150V N-Channel MOSFET

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
150V	9m Ω @10V	90A

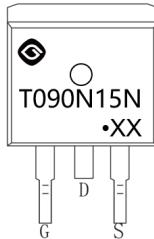
Feature

- Split Gate Trench Technology
- Low $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested

Application

- Power Switching Application

MARKING:

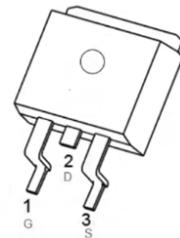


T090N15N = Device Code

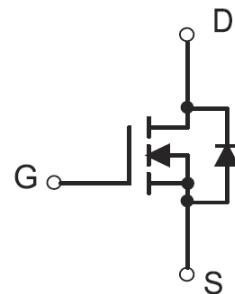
XX = Date Code

Solid Dot = Green Indicator

TO-263-2L



Schematic diagram



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

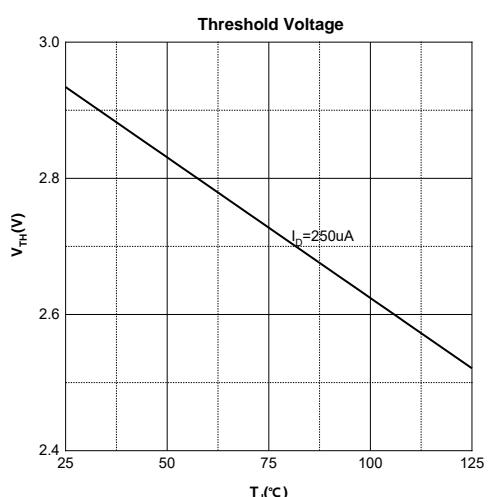
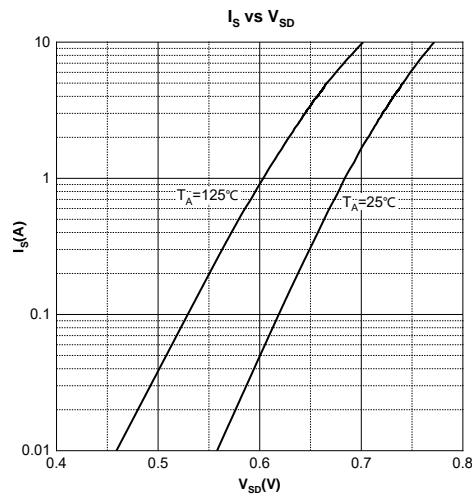
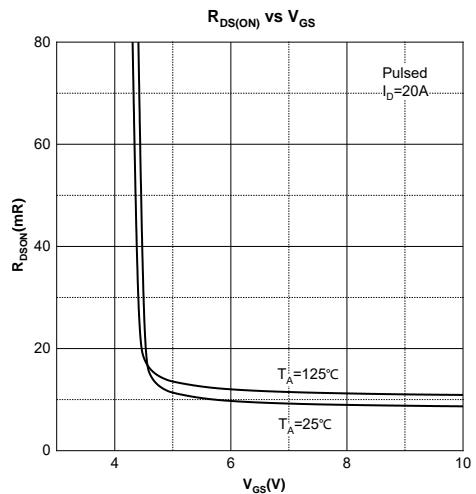
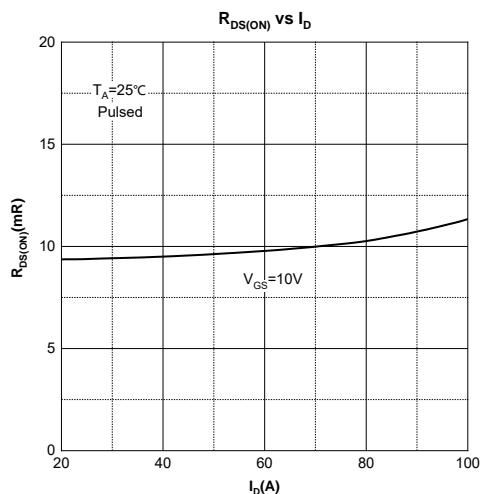
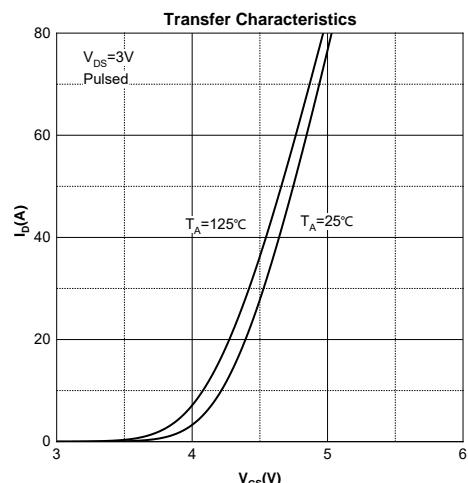
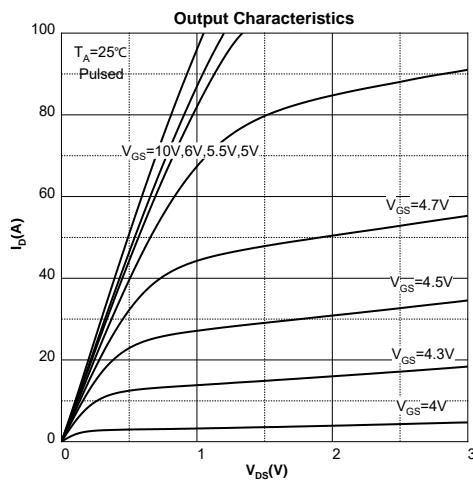
Parameter	Symbol	Value	Unit
Drain - Source Voltage	V_{DS}	150	V
Gate - Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ¹	I_D	90	A
	I_D	59	A
Pulsed Drain Current ²	I_{DM}	360	A
Single Pulsed Avalanche Current ³	I_{AS}	36	A
Single Pulsed Avalanche Energy ³	E_{AS}	324	mJ
Power Dissipation ⁵	P_D	208	W
Thermal Resistance from Junction to Ambient ⁶	$R_{\theta JA}$	30	$^\circ\text{C}/\text{W}$
Thermal Resistance from Junction to Case	$R_{\theta JC}$	0.6	$^\circ\text{C}/\text{W}$
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55~+150	$^\circ\text{C}$

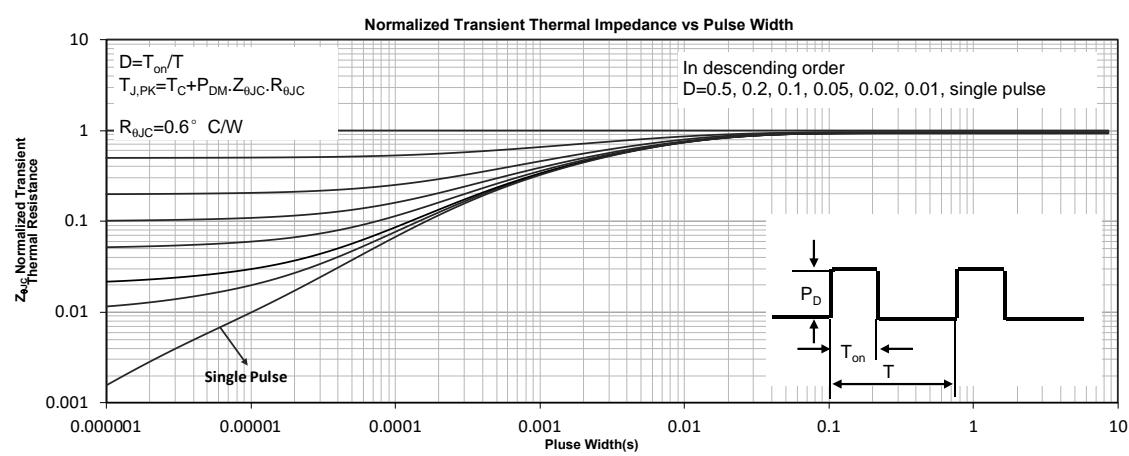
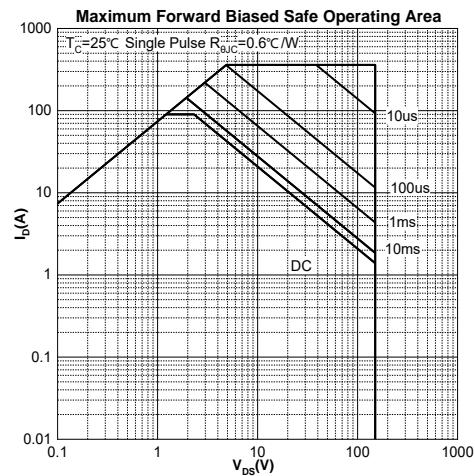
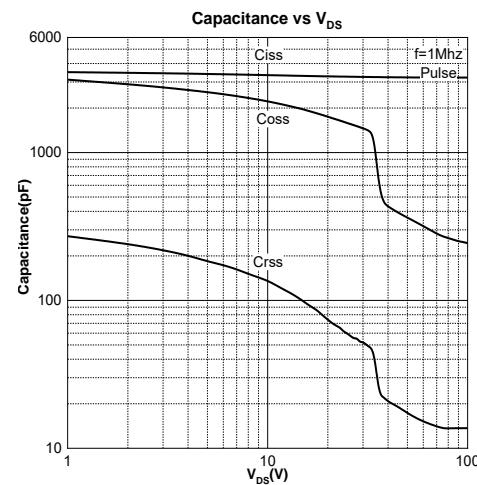
MOSFET ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

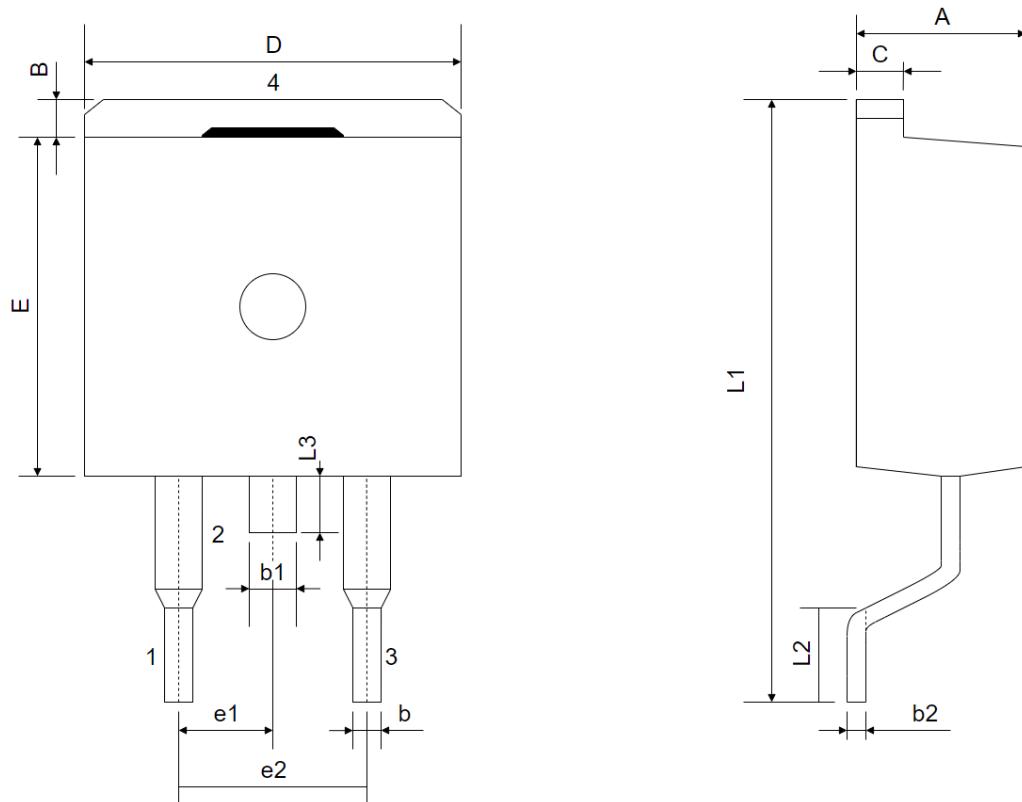
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Off Characteristics						
Drain - Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0V, I_D = 250\mu\text{A}$	150			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 150\text{V}, V_{GS} = 0\text{V}$			1	μA
Gate - Body Leakage Current	I_{GSS}	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$			± 100	nA
On Characteristics⁴						
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	2	3	4	V
Drain-source On-resistance	$R_{DS(\text{on})}$	$V_{GS} = 10\text{V}, I_D = 20\text{A}$		9	12	$\text{m}\Omega$
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS} = 75\text{V}, V_{GS} = 0\text{V}, f = 0.1\text{MHz}$		3256		pF
Output Capacitance	C_{oss}			280		
Reverse Transfer Capacitance	C_{rss}			19		
Gate Resistance	R_g	$V_{DS} = 0\text{V}, V_{GS} = 0\text{V}, f = 0.1\text{MHz}$		3		Ω
Switching Characteristics						
Total Gate Charge	Q_g	$V_{DS} = 75\text{V}, V_{GS} = 10\text{V}, I_D = 20\text{A}$		54		nC
Gate-source Charge	Q_{gs}			21		
Gate-drain Charge	Q_{gd}			10		
Turn-on Delay Time	$t_{d(\text{on})}$	$V_{DD} = 75\text{V}, V_{GS} = 10\text{V}, I_D = 45\text{A}, R_G = 2.2\Omega$		17		ns
Turn-on Rise Time	t_r			80		
Turn-off Delay Time	$t_{d(\text{off})}$			36		
Turn-off Fall Time	t_f			10		
Source - Drain Diode Characteristics						
Diode Forward Voltage ⁴	V_{SD}	$V_{GS} = 0\text{V}, I_s = 20\text{A}$			1.2	V

Notes :

- 1.The maximum current rating is limited by package.And device mounted on a large heatsink
- 2.Pulse Test : Pulse Width $\leq 10\mu\text{s}$, duty cycle $\leq 1\%$.
- 3.E_{AS} condition: $V_{DD} = 50\text{V}, V_{GS} = 10\text{V}, L = 0.5\text{mH}, R_G = 25\Omega$ Starting $T_J = 25^\circ\text{C}$.
- 4.Pulse Test : Pulse Width $\leq 1500\mu\text{s}$, duty cycle $\leq 2\%$.
- 5.The power dissipation P_D is limited by $T_{J(\text{MAX})} = 150^\circ\text{C}$.And device mounted on a large heatsink
- 6.Device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$.

Typical Characteristics




TO-263-2L Package Information


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.300	4.700	0.169	0.185
B	1.000	1.400	0.039	0.055
b	0.700	0.900	0.028	0.035
b1	1.150	1.350	0.045	0.053
b2	0.400	0.600	0.016	0.024
C	1.200	1.400	0.047	0.055
D	9.800	10.200	0.386	0.402
E	9.000	9.400	0.354	0.370
e1	2.340	2.740	0.092	0.108
e2	4.880	5.280	0.192	0.208
L1	15.000	16.000	0.591	0.630
L2	2.240	2.840	0.088	0.112
L3	1.200	1.600	0.047	0.063